

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current	I <sub>FM</sub>	500	mA
Average Rectified Output Current	I <sub>O</sub>	250	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	4.0	A
		1.0	

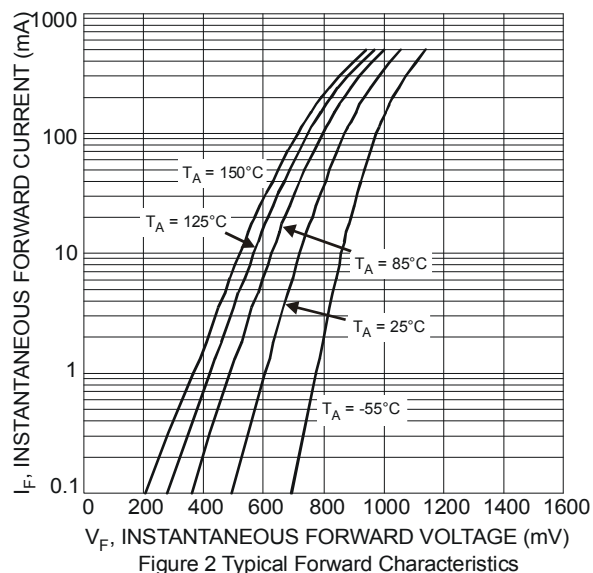
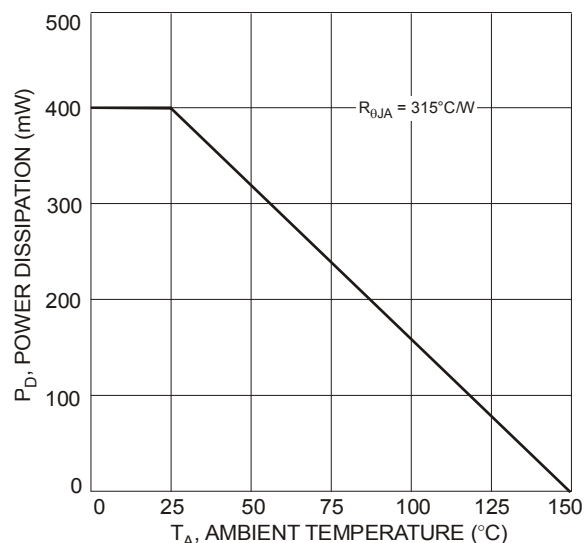
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	315	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 10μA
Forward Voltage	V <sub>FM</sub>	0.62	0.72	V	I <sub>F</sub> = 5.0mA
		—	0.855		I <sub>F</sub> = 10mA
		—	1.0		I <sub>F</sub> = 100mA
		—	1.25		I <sub>F</sub> = 150mA
Peak Reverse Current (Note 6)	I <sub>RM</sub>	—	2.5	μA	V <sub>R</sub> = 75V
			50	μA	V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C
			30	μA	V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C
			25	nA	V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	4.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 PC board with minimum recommended pad layout, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating effect.



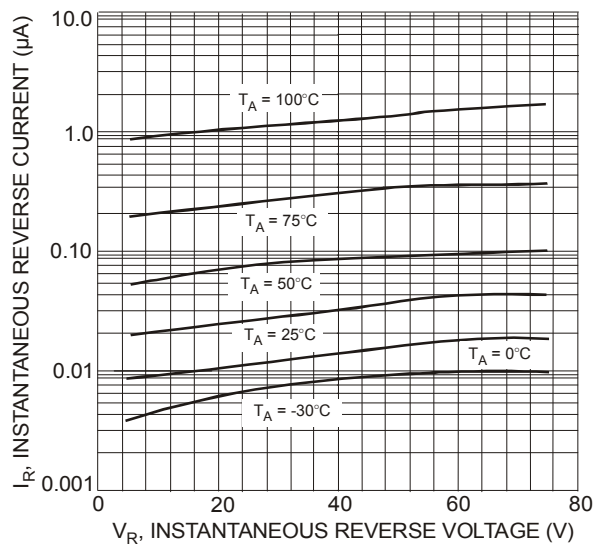


Fig. 3 Typical Reverse Characteristics

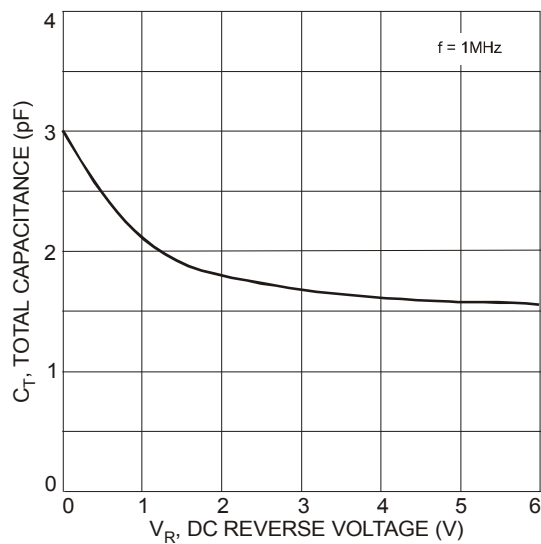


Fig. 4 Total Capacitance vs. Reverse Voltage

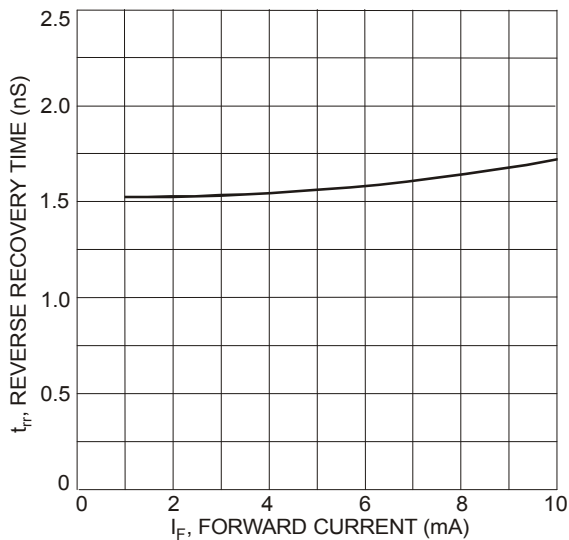
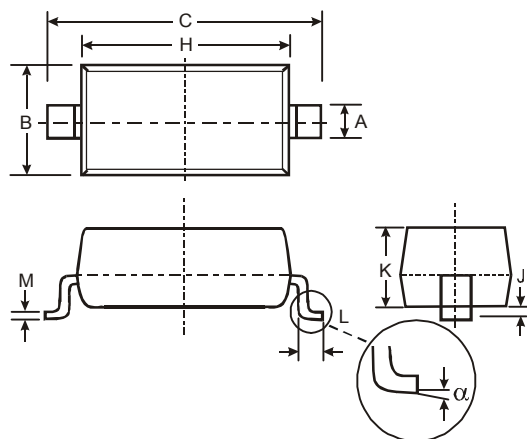


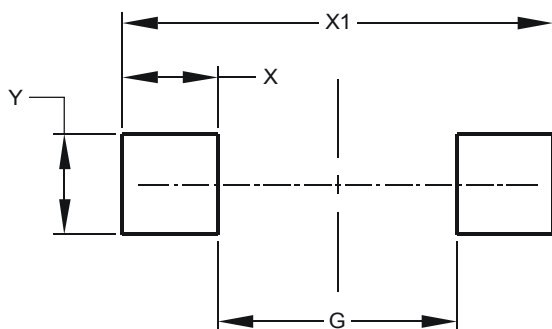
Fig. 5 Reverse Recovery Time vs. Forward Current

## Package Outline Dimensions



SOD-123		
Dim	Min	Max
A	0.55 Typ	
B	1.40	1.70
C	3.55	3.85
H	2.55	2.85
J	0.00	0.10
K	1.00	1.35
L	0.25	0.40
M	0.10	0.15
α	0	8°
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
<b>G</b>	2.250
<b>X</b>	0.900
<b>X1</b>	4.050
<b>Y</b>	0.950

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